

## FMS 2024: Exploring Memory and Storage Innovation with BIWIN

[Santa Clara, California, 2024/7/25]—At FMS 2024(**Future of Memory and Storage 2024**), Booth #619, BIWIN Storage Technology Co., Ltd. will present its latest advancements in memory and storage technology.

FMS 2024 will be held from August 6<sup>th</sup>-8<sup>th</sup>, 2024 at the Santa Clara Convention Center in California, in the heart of the famous Silicon Valley. This year FMS broadens its scope from flash memory to encompass a wider range of memory and storage technologies.



Appropriately, BIWIN will showcase its wide range of innovations and state-of-the-art solutions including industrial and consumer storage, embedded memory chips, and memory modules that address the evolving needs of the industry.

Top executives from BIWIN Headquarters and the Americas will be present at Booth #619 to exchange ideas, explore potential collaborations, and gain valuable insights into our latest technologies and solutions. On Wednesday, August 7<sup>th</sup>, in the FMS Theater in the Exhibit Hall, BIWIN will announce its latest industry cooperation.



Some of the product highlights included in BIWIN's presence at FMS 2024 will be:

### **Industrial Storage Solutions: Outstanding Durability and Performance**

**GS30 Series SATA SSD:** The BIWIN GS30 series 2.5" SSD, with SATA III interface, brings sequential read and write speeds up to 560 MB/s and 520 MB/s, respectively, with disk write speed maintained around 450 MB/s. This product ensures data safety and reliable storage in extreme temperatures and harsh environments with functions including power loss data protection, data inspection, end-to-end data protection, and data destruction.

**TGP200 Series PCIe SSD:** The TGP200 PCIe SSD features a DRAM-less design, supporting wide operation temperature from -40°C to 85°C and wide storage temperature from -55°C to 95°C. TGP200 series includes power loss protection (PLP) and boasts an MTBF of up to 3 million hours. With read and write speeds of up to 3400 MB/s and 2900 MB/s respectively, the TGP200 series meets the stringent requirements for efficient and reliable data storage in professional industrial environments.

**Industrial eMMC:** The BIWIN industrial eMMC is an advanced storage solution that integrates NAND flash memory, a sophisticated flash controller, and a fast Multi Media Card (MMC) interface in the same package. The BIWIN eMMC features Command Queuing and SLC Cache to enhance random read/write performance; high speed 400 (HS400) DDR Mode; and field firmware update

(FFU). It ensures quality assurance for industrial standards, supports customization in both software and hardware, and guarantees long-term and stable supply.

**Industrial SD Card TGC207 & microSD Card TGC209:** Industrial SD TGC207 and microSD 209 (designed specifically for video surveillance applications) utilize SIP-level packaging and operate within a wide temperature range of -40°C to 85°C. These cards feature an integrated LDPC ECC Engine and boast extensive TBW, ensuring continuous video recording. They excel in stable multi-channel video writing without frame drops and incorporate firmware enhancements for abnormal power-off data protection, guaranteeing normal operation during critical moments.

### **PC OEM Solutions: Cutting-Edge Technology for Superior Systems**

**AP843 PCIe SSD:** Our cutting-edge PC OEM solution, is designed to elevate the experience with unmatched reliability, efficiency, and performance. The BIWIN AP843 leverages high-quality original manufacturer die, comprehensive feature analysis, and optimized temperature management to ensure exceptional NAND reliability. With low power consumption, it supports modern standby modes, keeping systems ready while conserving energy. The AP843 offers stable performance, optimizing OS disk scenarios and maintaining consistent performance even in complex applications. It also includes advanced security and data protection, supporting RAID configurations, device self-tests, and advanced end-to-end protection technologies.

**LPCAMM2 DDR5 Memory:** LPCAMM2 is the next generation of compressed additional DDR5 memory modules which brings data transfer speeds up to 9600 MT/s+. Suitable for new laptops, mini PCs, edge computing, and compact devices, LPCAMM2 answers the need for more IO-intensive computational operation in office work, visual modeling, editing, and gaming-- and also supports high-performance AI computing to aid in training models of deep learning.

**CU-DIMM DDR5 Memory:** The CU-DIMM DDR5 desktop memory enhances the traditional DDR5 memory by adding a Client Clock Driver (CKD) chip which buffers and then drives the memory clock signal, improving signal integrity. This breakthrough allows memory module speeds to exceed the 6400 MT/s bottleneck, enhancing memory bandwidth to meet the demands of more IO-intensive computations. It ensures smoother operation for office tasks,

modeling, editing, gaming, and AI computing.

**Meet BIWIN at FMS 2024 and check out BIWIN's industry-leading products featuring strong performance, lower power consumption, great reliability, and larger capacity to meet your storage needs.**

## **About BIWIN STORAGE TECHNOLOGY**

BIWIN Storage Technology Company Limited produces high-quality flash storage and is now known in embedded, consumer, corporate and industrial segments for its independent development capabilities in hardware, software, firmware, and storage algorithms.

BIWIN's experience in production (along with its complete packaging, testing, and production lines) ensures BIWIN products are superior in performance, earning BIWIN many awards and a reputation for providing global customers with high-quality storage products.

Recently the company opened its latest facility, BIWIN Huizhou Science and Technology Zone, with a state-of-the-art 110,000 m<sup>2</sup> facility.



Our founders started in the flash storage business in Shenzhen, China in 1995, embracing the “WIN-WIN” business philosophy that would later become a hallmark for BIWIN. In 2009 they made a key decision for the business: to add

IC encapsulation (IC packaging process) into the factory. This remarkable milestone-- that the vast majority of competing companies still don't have (they outsource the process or buy the packaged IC) -- led to success and the 2010 creation of the company we know today: BIWIN Storage Technology Company Limited.

After a successful IPO, BIWIN is now listed on the Shanghai Stock Exchange, STAR Market on the Sci-tech Innovation Board. Stock Symbol: 688525.

For logo and photos, please download from [this folder](#).

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To learn more about BIWIN, visit <https://biwintechnology.com> or contact us at [mkt.hq@biwintech.com](mailto:mkt.hq@biwintech.com).